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Finetech's Lambda Bonder Enhances Advanced Packaging Capabilities at Lurie Nanofabrication Facility

GILBERT, AZ and Ann Arbor, Michigan - June 23, 2016 - [Finetech](#), a global supplier of micro-assembly equipment, and the University of Michigan in Ann Arbor, Michigan, announce the installation of a [FINEPLACER® Lambda](#) bonding system in the university's [Lurie Nanofabrication Facility](#) (LNF). This sub-micron accuracy bonder is designed to position and attach micro-electronic or opto-electronic components on various substrates, including flex circuits, glass, silicon, ceramic, etc.

LNF selected the Lambda bonder to support advanced packaging activities in its state-of-the-art micro and nanofabrication center. The 13,500 sf facility, comparable to the best in the world, is used by hundreds of students and researchers at the University of Michigan, other academic institutions, national labs and industry. This lab excels at combining technologies and materials within a single device, for example, optical or mechanical sensors with integrated processing circuitry and on board power generation.



With a wide base of installations at many prestigious institutions and research centers, Finetech's die bonders provide unmatched solutions for advanced technology environments utilizing diverse applications. The Lambda is a semi-automated bonding platform that is ideal for product and process development of photonics devices, sensors, LED bonding, MEMs, flip chip and micro optics assembly. Bonding technologies supported by the system include thermocompression, thermosonic, ultrasonic, adhesives, curing and soldering (AuSn, C4, Indium, eutectic).

"We chose the Finetech Lambda based on the system's process flexibility, accuracy, ease of use, and reliability - important factors in an active multi-user environment," stated Pilar Herrera-Fierro, User Services Director at LNF. "The sub-micron placement capability is critical for our research being done in areas such as silicon integrated circuits, optoelectronics, MEMS, Bio-MEMS and microfluidics."

About Finetech

Finetech is a leading manufacturer of equipment for manual and fully automatic high-precision die bonding and component rework. The company services customers in a broad range of industries including aerospace, medical technology, consumer electronics, semiconductor, optoelectronics, military, universities and research. Corporate headquarters and main production are in Berlin, Germany. Sales and Technical support centers are located in Tempe, Arizona; Manchester, New Hampshire; Shanghai, China and Kuala Lumpur, Malaysia.

To learn more about the company please visit www.finetechusa.com. To learn more about the FINEPLACER® lambda bonding system please [click here](#).

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About Lurie Nanofabrication Facility

The Lurie Nanofabrication Facility (LNF) provides access to advanced nanofabrication equipment and expertise, promoting and enabling cutting-edge education, research and development from materials and individual process steps to entire systems. The LNF is available, on a fee basis, for use by research groups from government, industry and universities. The facility is supported by a highly trained group of engineers and technicians who ensure that the equipment is well maintained and characterized while domain experts provide comprehensive support to users and their projects.

For further information about LNF, visit: LNF.umich.edu.

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